bq25895M I²C Controlled Single Cell Fast Charger with MaxCharge™ Technology for High Input Voltage

1 Features

- High Efficiency 1.5-MHz Switch Mode Buck Charge
  - 93% Charge Efficiency at 2 A and 91% Charge Efficiency at 3 A Charge Current
  - Optimize for High Voltage Input (9 V / 12 V)
  - Low Power PFM mode for Light Load Operations
- Boost Mode Operation with Adjustable Output from 4.5 V to 5.5 V
  - Selectable 500-KHz / 1.5-MHz Boost Converter with up-to 3.1 A Output
  - 93% Boost Efficiency at 5 V at 1 A Output
  - Support down-to 2.5V Battery
  - Support PWM only or PFM/PWM control for Light Load Efficiency
- Integrated Control to Switch Between Charge and Boost Mode
- Single Input to Support USB Input and Adjustable High Voltage Adapters
  - Support 3.9-V to 14-V Input Voltage Range
  - Input Current Limit (100 mA to 3.25 A with 50-mA resolution) to Support USB2.0, USB3.0 standard and High Voltage Adapters
  - Maximum Power Tracking by Input Voltage Limit up-to 14V for Wide Range of Adapters
- Input Current Optimizer (ICO) to Maximize Input Power without Overloading Adapters
- Resistance Compensation (IRCOMP) from Charger Output to Cell Terminal
- Highest Battery Discharge Efficiency with 11-mΩ Battery Discharge MOSFET up to 9 A
- Integrated ADC for System Monitor (Voltage, Temperature, Charge Current)
- BATFET Control to Support Ship Mode, Wake Up, and Full System Reset
- Flexible Autonomous and I²C Mode for Optimal System Performance
- High Integration includes all MOSFETs, Current Sensing and Loop Compensation
- 12-µA Low Battery Leakage Current to Support Ship Mode
- High Accuracy
  - ±0.5% Charge Voltage Regulation
  - ±5% Charge Current Regulation
  - ±7.5% Input Current Regulation
- Safety
  - Battery Temperature Sensing for Charge and Boost Mode
  - Thermal Regulation and Thermal Shutdown

2 Applications

- Power Bank, Mobile Wi-Fi Hotspot
- Wireless Bluetooth Speaker
- Portable Internet Devices

3 Description

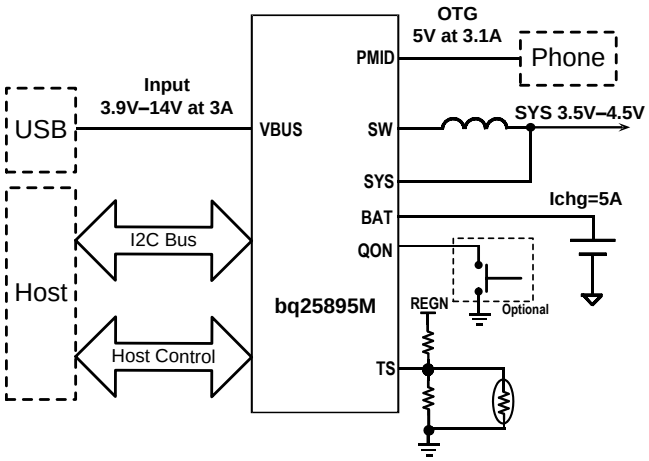
The bq25895M is a highly-integrated 5-A switch-mode battery charge management and system power path management device for single cell Li-Ion and Li-polymer battery. The devices support high input voltage fast charging. The low impedance power path optimizes switch-mode operation efficiency, reduces battery charging time and extends battery life during discharging phase. The I²C Serial interface with charging and system settings makes the device a truly flexible solution.

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
bq25895M	WQFN (24)	4.00mm x 4.00mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

Simplified Schematic



4 Revision History

DATE	REVISION	NOTES
July 2015	*	Initial release.

5 Description (Continued)

The bq25895M is a highly-integrated 5-A switch-mode battery charge management and system power path management device for single cell Li-Ion and Li-polymer battery. It features fast charging with high input voltage support for a wide range of smartphone, tablet and portable devices. Its low impedance power path optimizes switch-mode operation efficiency, reduces battery charging time and extends battery life during discharging phase. It also integrates Input Current Optimizer (ICO) and Resistance Compensation (IRCOMP) to deliver maximum charging power to battery. The solution is highly integrated with input reverse-blocking FET (RBFET, Q1), high-side switching FET (HSFET, Q2), low-side switching FET (LSFET, Q3), and battery FET (BATFET, Q4) between system and battery. It also integrates the bootstrap diode for the high-side gate drive and battery monitor for simplified system design. The I^2C serial interface with charging and system settings makes the device a truly flexible solution

The device supports a wide range of input sources, including standard USB host port, USB charging port, and USB compliant adjustable high voltage adapter. To support fast charging using adjustable high voltage adapter, the bq25895M provides support MaxCharge™ handshake using D+/D- pins and DSEL pin for USB switch control. In addition, the device includes interface to support adjustable high voltage adapter using input current pulse protocol. To set the default input current limit, device uses the built-in USB interface. The device is compliant with USB 2.0 and USB 3.0 power spec with input current and voltage regulation. In addition, the Input Current Optimizer (ICO) supports the detection of maximum power point detection of the input source without overload. The device supports battery boost operation by supplying adjustable 4.5V-5.5V on PMID pin with up to 3.1A with integrated charge and boost mode detection

The power path management regulates the system slightly above battery voltage but does not drop below 3.5V minimum system voltage (programmable). With this feature, the system maintains operation even when the battery is completely depleted or removed. When the input current limit or voltage limit is reached, the power path management automatically reduces the charge current to zero. As the system load continues to increase, the power path discharges the battery until the system power requirement is met. This operation prevents overloading the input source.

The device initiates and completes a charging cycle without software control. It automatically detects the battery voltage and charges the battery in three phases: pre-conditioning, constant current and constant voltage. At the end of the charging cycle, the charger automatically terminates when the charge current is below a preset limit in the constant voltage phase. When the full battery falls below the recharge threshold, the charger will automatically start another charging cycle.

The charger provides various safety features for battery charging and system operations, including battery temperature negative thermistor monitoring, charging safety timer and overvoltage/overcurrent protections. The thermal regulation reduces charge current when the junction temperature exceeds 120°C (programmable). The STAT output reports the charging status and any fault conditions. The INT immediately notifies host when fault occurs.

The device also provides a 7-bit analog-to-digital converter (ADC) for monitoring charge current and input/battery/system (VBUS, BAT, SYS, TS) voltages. The QON pin provides BATFET enable/resôet control to exit low power ship mode or full system reset function.

The device family is available in 24-pin, 4 x 4 mm^2 x 0.75 mm thin WQFN package.

6 Device and Documentation Support

6.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

6.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community ***TI's Engineer-to-Engineer (E2E) Community.*** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support ***TI's Design Support*** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

6.3 Trademarks

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

6.4 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

6.5 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

7 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
BQ25895MRTWR	ACTIVE	WQFN	RTW	24	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	BQ 25895M	Samples
BQ25895MRTWT	ACTIVE	WQFN	RTW	24	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	BQ 25895M	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

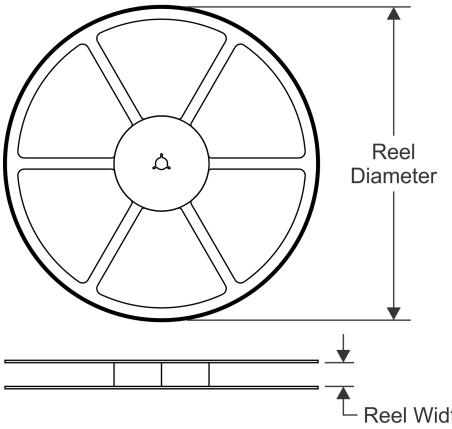
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

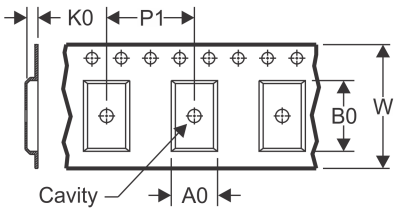
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

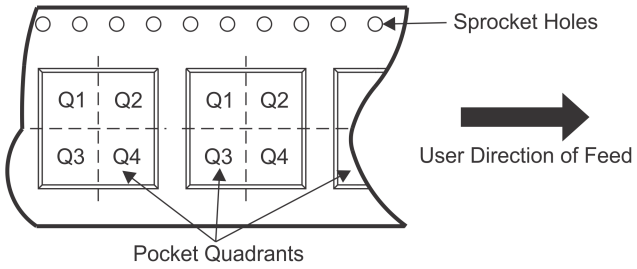


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

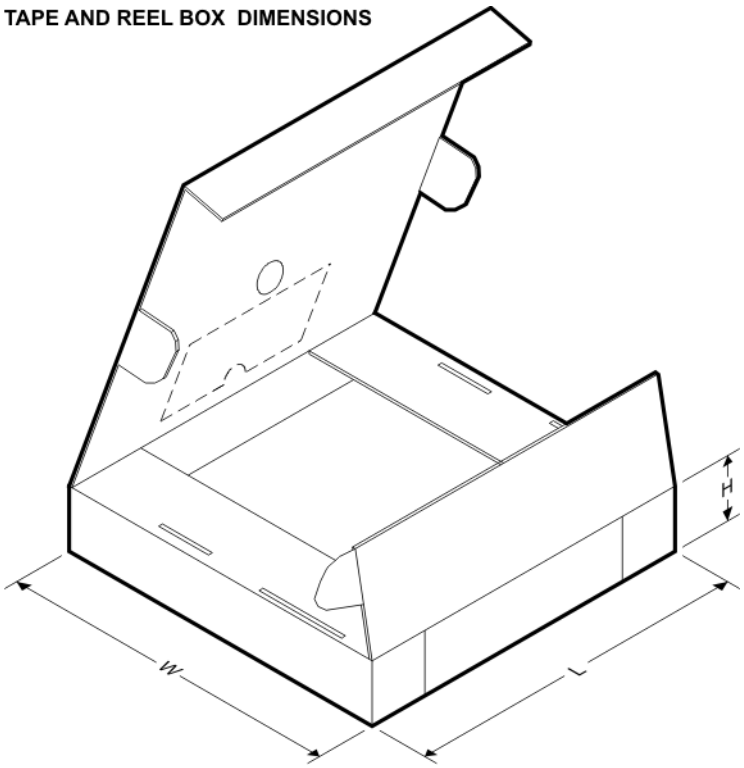
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BQ25895MRTWR	WQFN	RTW	24	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
BQ25895MRTWT	WQFN	RTW	24	250	180.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2

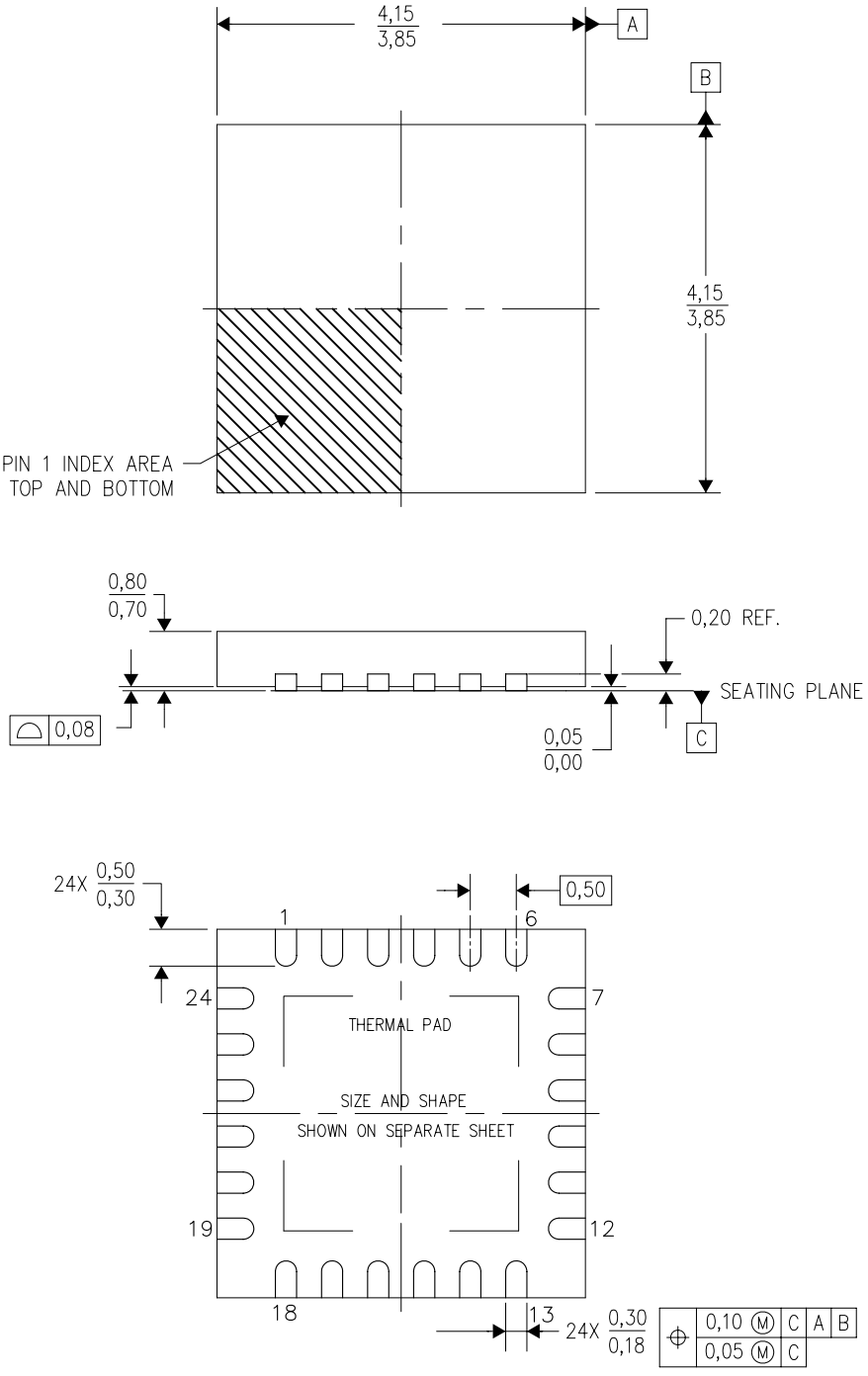
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
BQ25895MRTWR	WQFN	RTW	24	3000	367.0	367.0	35.0
BQ25895MRTWT	WQFN	RTW	24	250	210.0	185.0	35.0

RTW (S–PWQFN–N24) PLASTIC QUAD FLATPACK NO–LEAD



NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Quad Flatpack, No–Leads (QFN) package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
F. Falls within JEDEC MO–220.

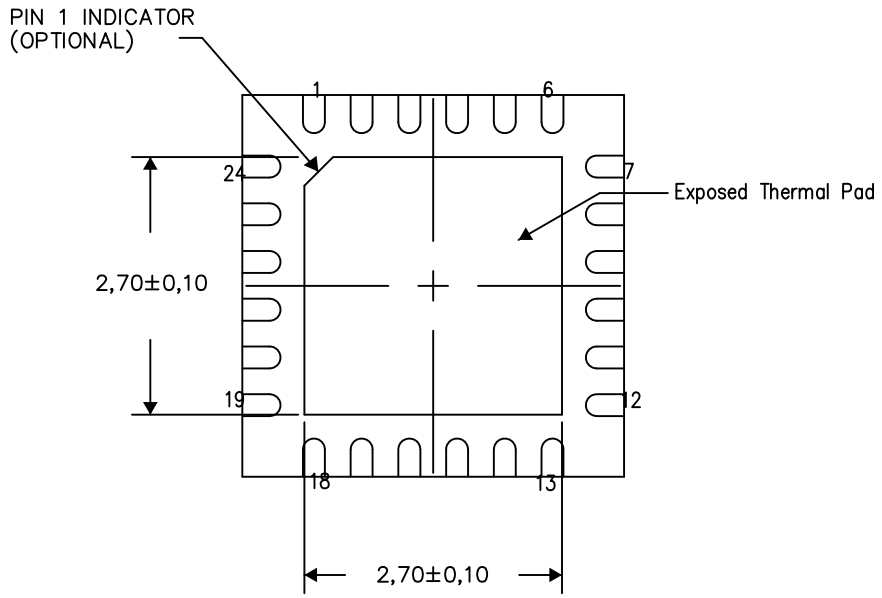
RTW (S–PWQFN–N24) PLASTIC QUAD FLATPACK NO–LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No–Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



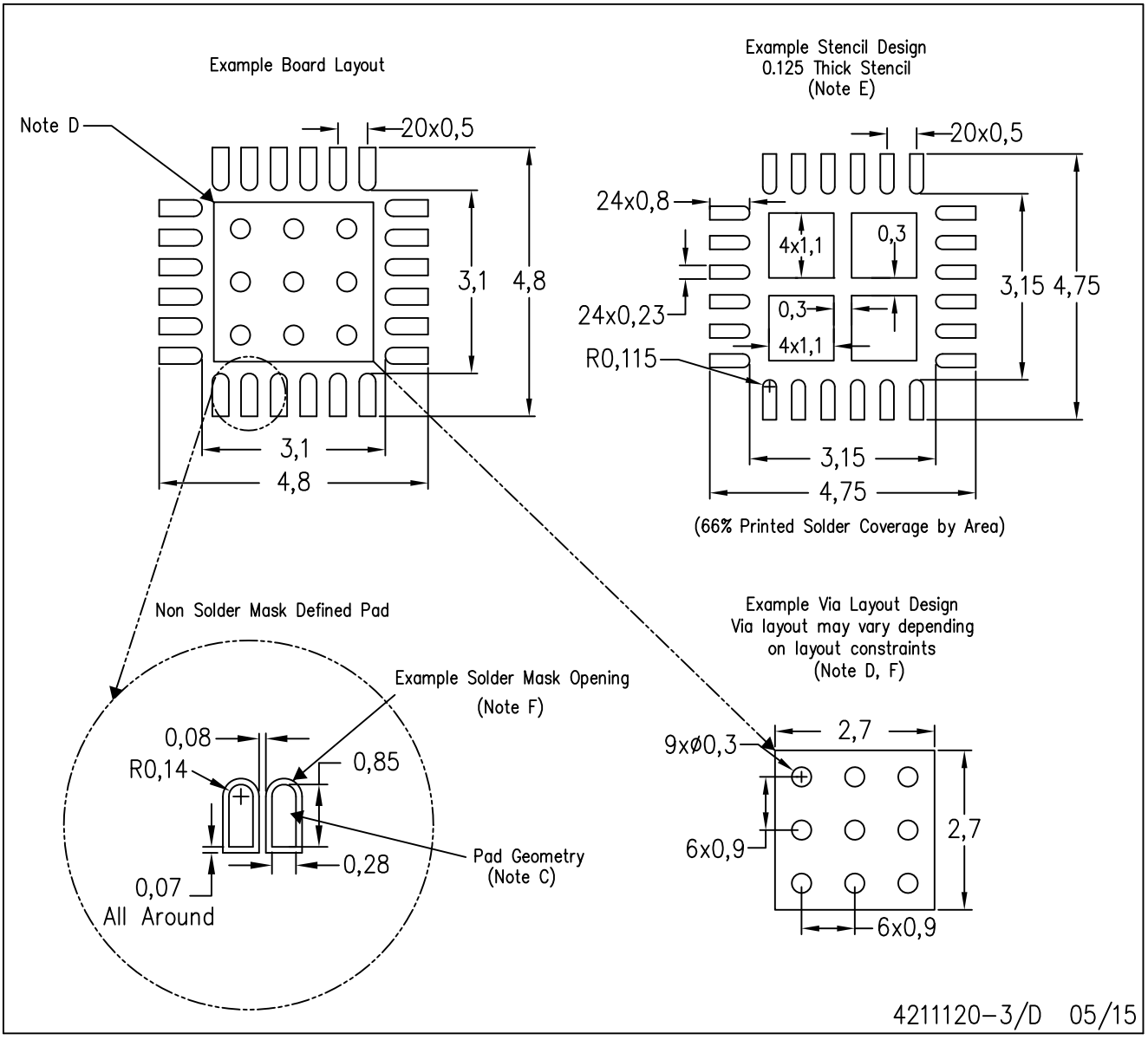
Bottom View

Exposed Thermal Pad Dimensions

4206249–5/P 05/15

NOTES: A. All linear dimensions are in millimeters

RTW (S–PWQFN–N24) PLASTIC QUAD FLATPACK NO–LEAD



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat–Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http://www.ti.com>.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
F. Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.

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